MFlex

Introduction

MFlex is an electrodeposited copper foil for application on acrylic and polyester flex substrates. This product is designed for flex-to-install applications. MFlex meets all requirements of IPC Grade 2 copper foils.

Benefits

- Excellent peel strengths to enhance PCB reliability
- Lower profile for improved etching
- Cost-effective alternative to wrought and annealed foils

Typical Physical Characteristics

Oak-Mitsui foils meet all requirements of IPC-4562 and are produced with the patented "AT" resin resistant treatment.

Nominal Thickness Area Weight		microns oz/ft²	18 1/2	35 1	70 2
Tensile	ambient 180ºC	Kpsi Kpsi	60 30	55 30	52.5 30
Elongation	ambient 180ºC	%E %E	8 8	15 8	20 8
Roughness	drum matte	Ra Rmax	10 200	10 300	10 450
Peel Strength B Epoxy, Tg 170ºC	matte	lbs/in	7.5	10.5	15

The information contained in this specification is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose. The actual performance of Mitsui materials will vary according to the customer's application.